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(54) **BRIDGES FOR INTERCONNECTING INTERPOSERS IN MULTI-CHIP INTEGRATED CIRCUITS**

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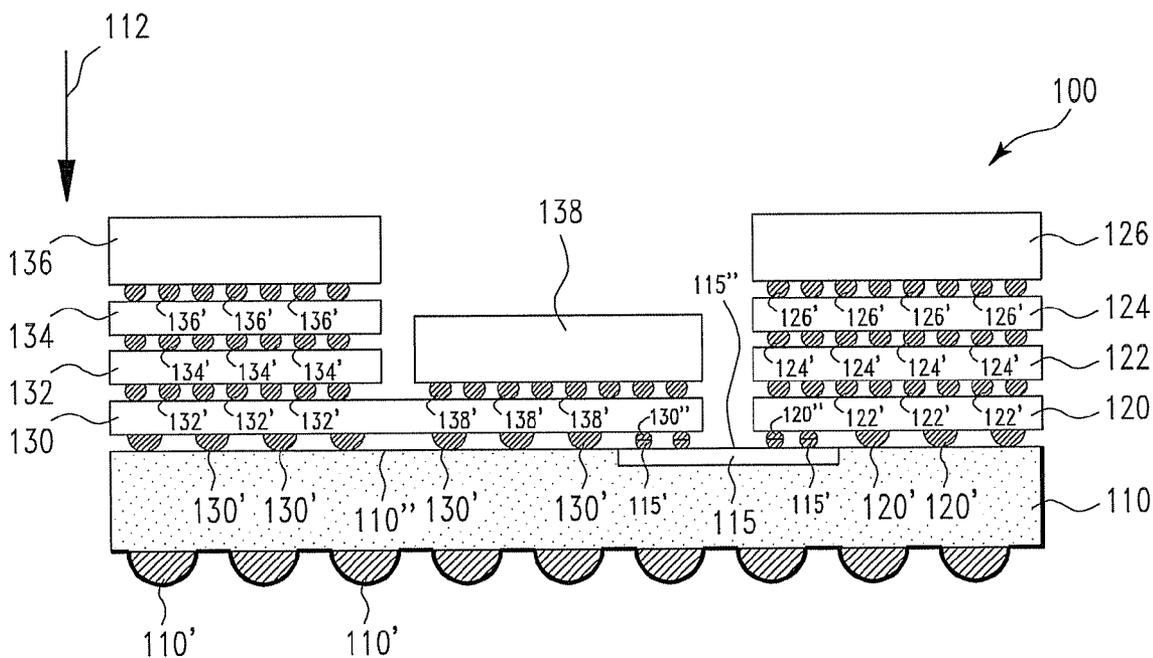
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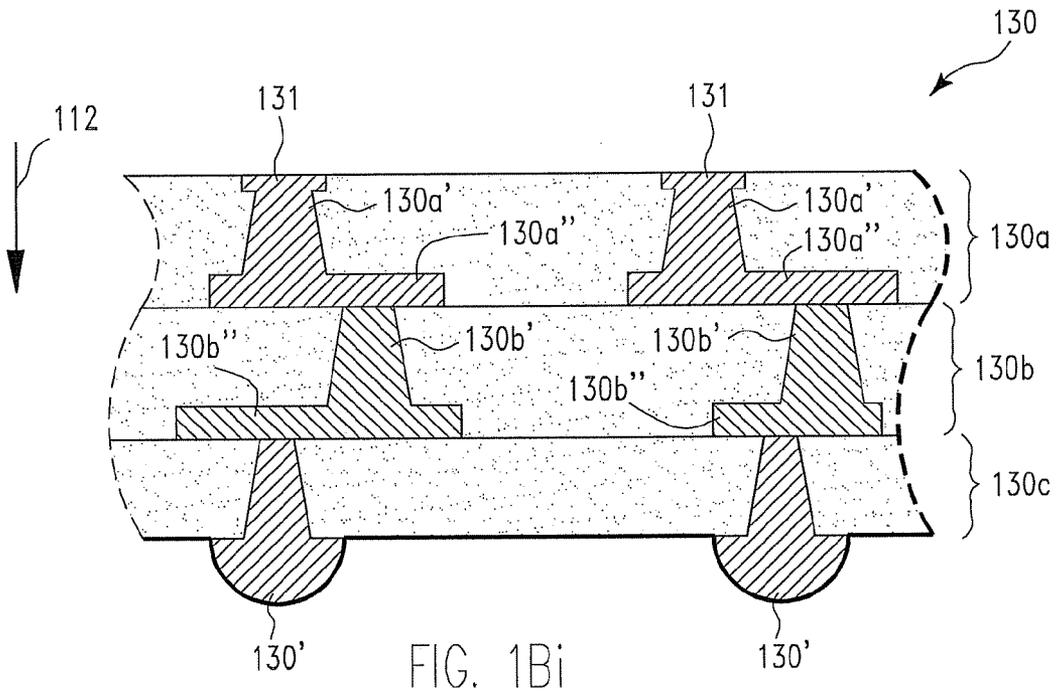
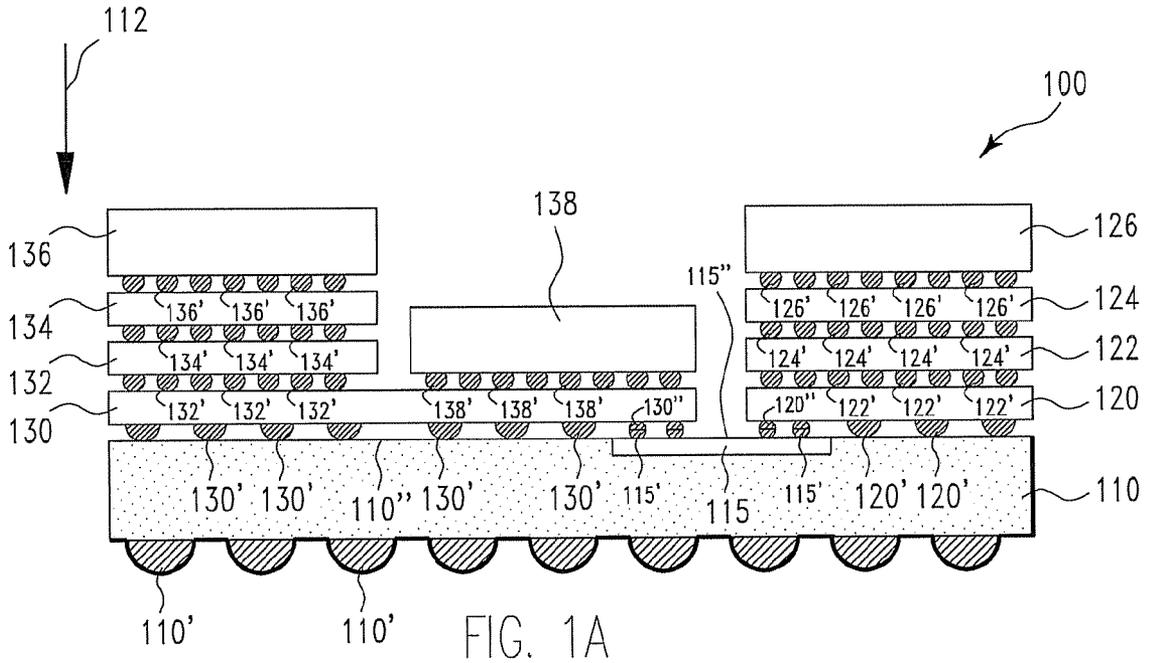
(57) **ABSTRACT**

A structure and a method for forming the same. The structure includes a substrate, a first interposer on the substrate, a second interposer on the substrate, and a first bridge. The first and second interposers are electrically connected to the substrate. The first bridge is electrically connected to the first and second interposers.

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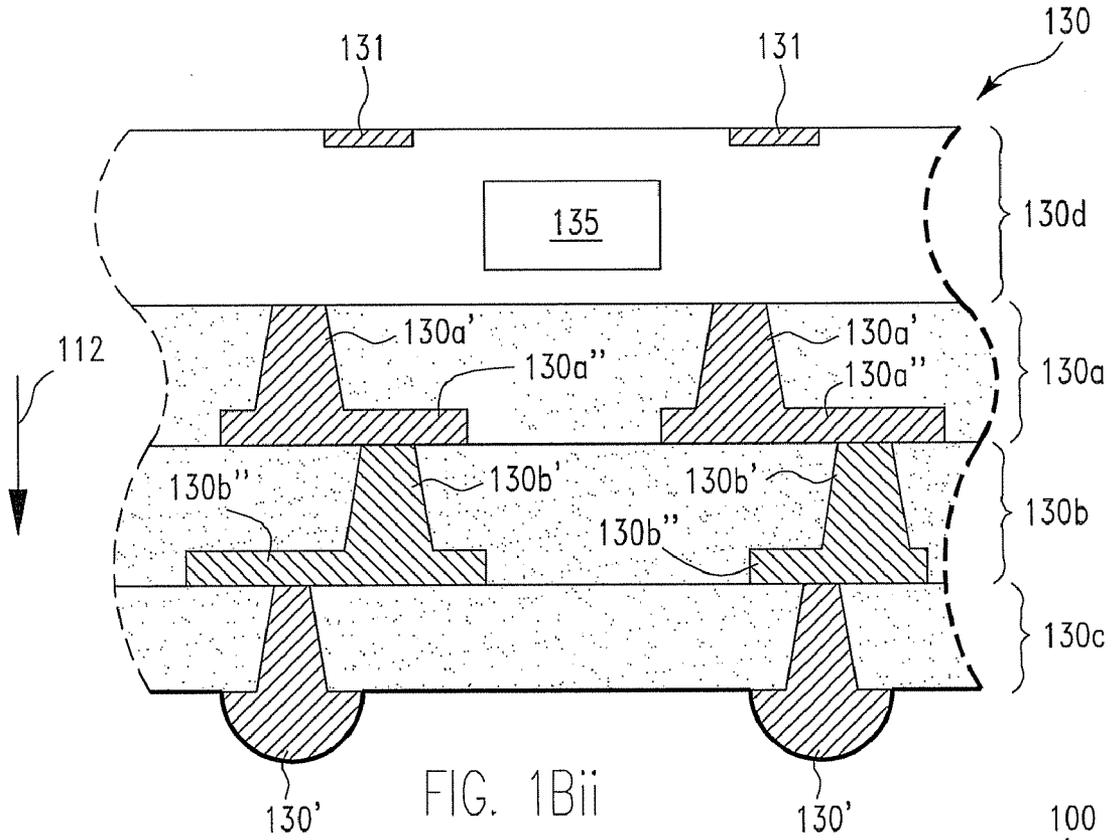


FIG. 1Bii

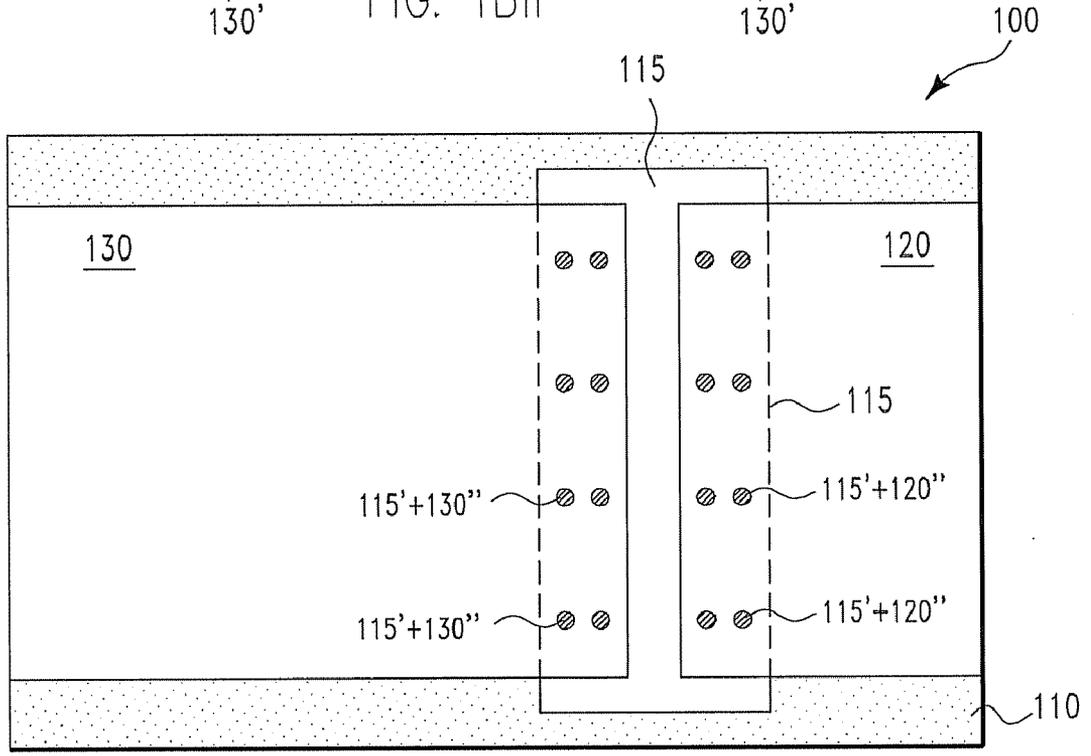
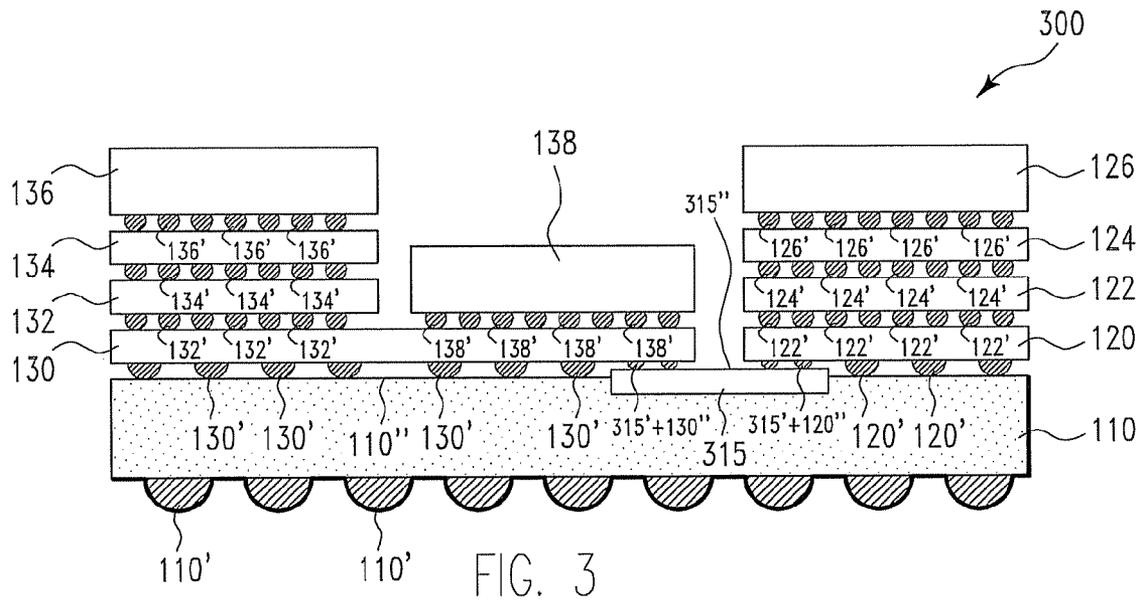
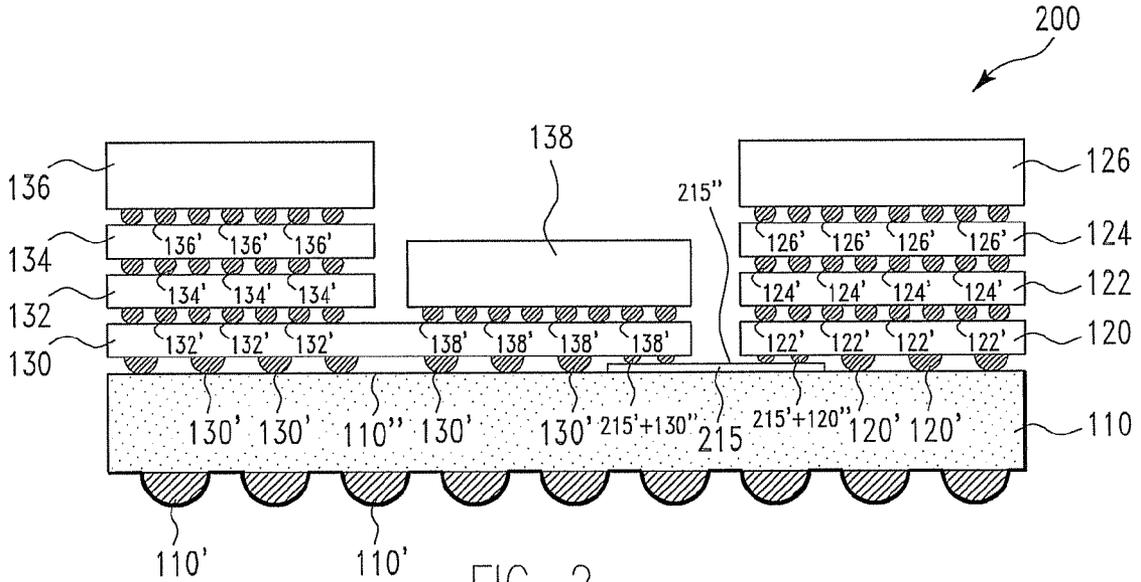
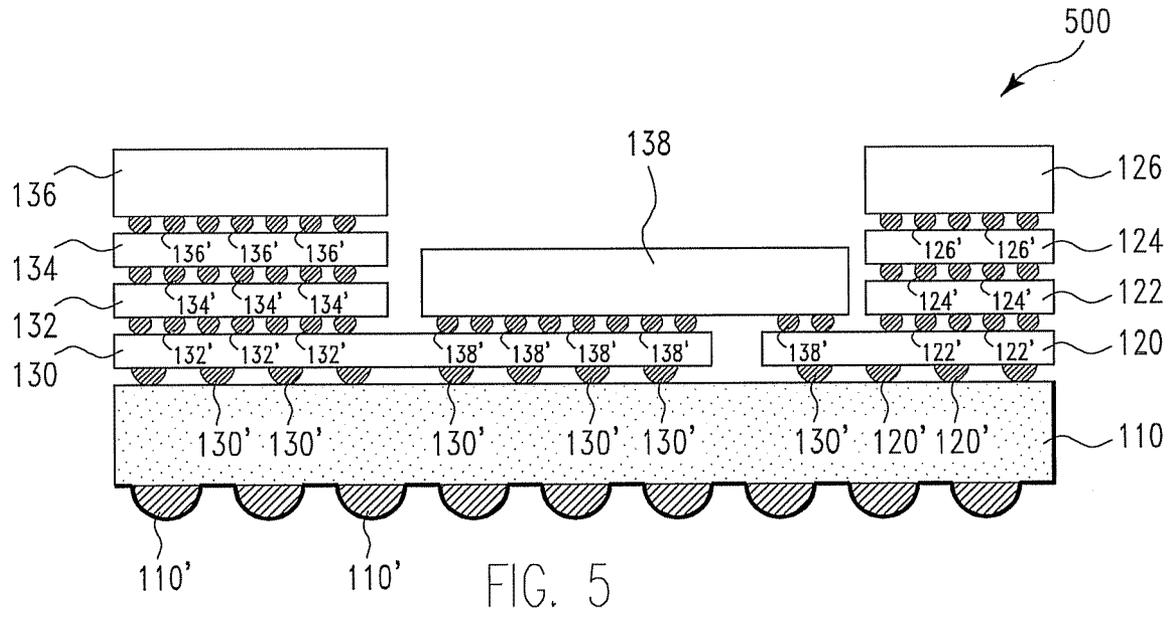
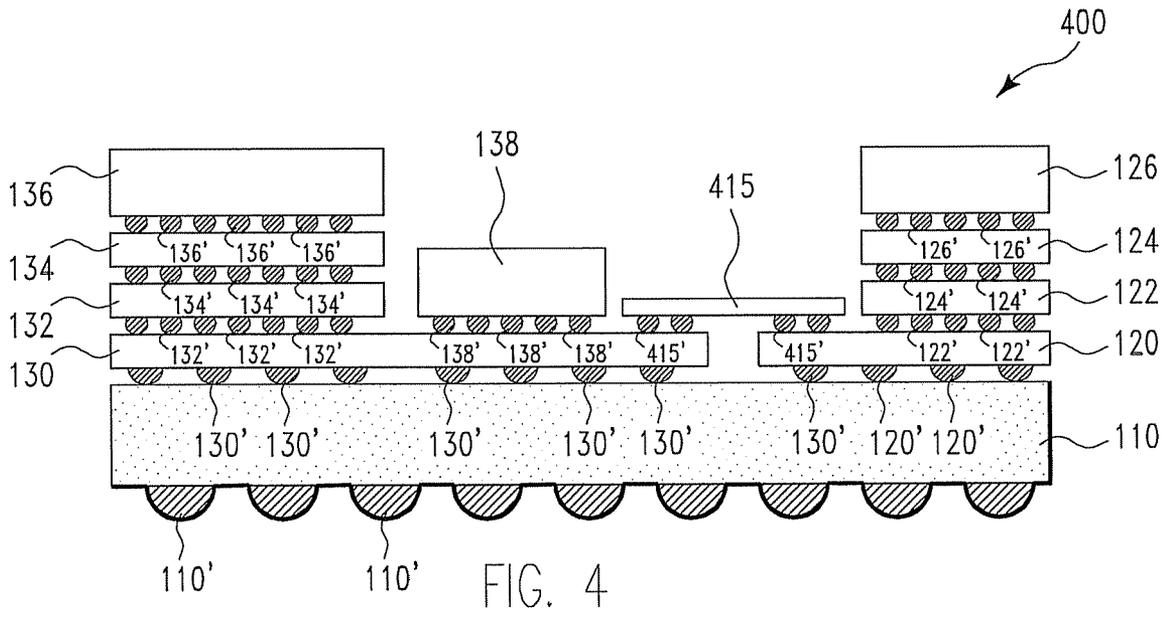


FIG. 1C





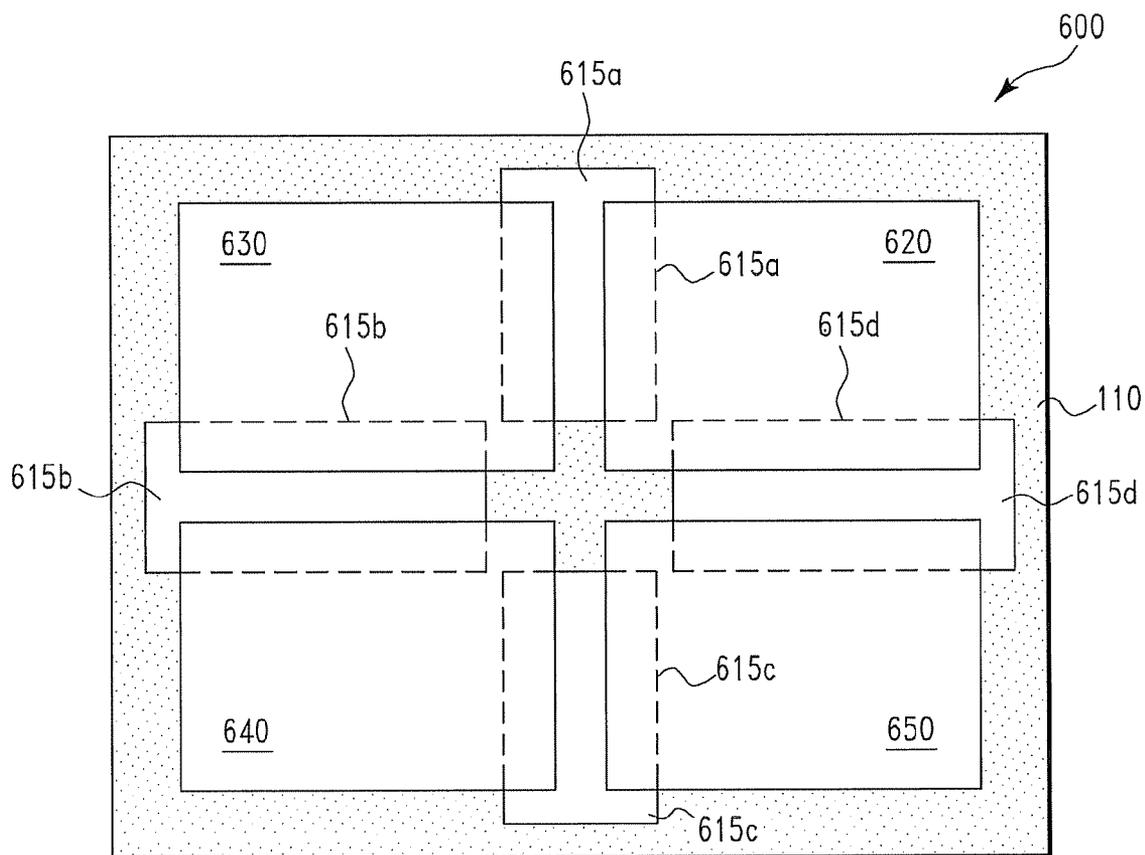


FIG. 6

**BRIDGES FOR INTERCONNECTING
INTERPOSERS IN MULTI-CHIP
INTEGRATED CIRCUITS**

[0001] This invention was made with Government support under Contract No.: H98 230-07-C-0409 awarded by RES National Security Agency. The Government has certain rights in this invention.

FIELD OF THE INVENTION

[0002] The present invention relates generally to multi-chip integrated circuits and more particularly to silicon bridge interconnections for interconnecting interposers in multi-chip integrated circuits.

BACKGROUND OF THE INVENTION

[0003] In a typical multi-chip integrated circuit, interposers may be used to electrically connect the chips to the substrate. In other words, the chips can communicate with one another via the substrate. However, the bandwidth of the substrate is limited. Therefore, there is a need for a structure (and a method for forming the same) in which more communication channels between the chips are provided than in the prior art.

SUMMARY OF THE INVENTION

[0004] The present invention provides a structure, comprising a substrate; a first interposer on the substrate, wherein the first interposer is electrically connected to the substrate; a second interposer on the substrate, wherein the second interposer is electrically connected to the substrate; and a first bridge electrically connected to the first and second interposers.

[0005] The present invention provides a structure (and a method for forming the same) in which more communication channels in the chip are provided than in the prior art.

BRIEF DESCRIPTION OF THE DRAWINGS

[0006] FIG. 1A shows a cross-section view of a first semiconductor structure, in accordance with embodiments of the present invention.

[0007] FIGS. 1Bi and 1Bii show cross-section views of two alternative embodiment of an interposer of the first semiconductor structure of FIG. 1A, in accordance with embodiments of the present invention.

[0008] FIG. 1C shows a top-down view of the first semiconductor structure of FIG. 1A, in accordance with embodiments of the present invention.

[0009] FIG. 2 shows a cross-section view of a second semiconductor structure, in accordance with embodiments of the present invention.

[0010] FIG. 3 shows a cross-section view of a third semiconductor structure, in accordance with embodiments of the present invention.

[0011] FIG. 4 shows a cross-section view of a fourth semiconductor structure, in accordance with embodiments of the present invention.

[0012] FIG. 5 shows a cross-section view of a fifth semiconductor structure, in accordance with embodiments of the present invention.

[0013] FIG. 6 shows a top-down view of a sixth semiconductor structure, in accordance with embodiments of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

[0014] FIG. 1A shows a cross-section view of a semiconductor structure 100, in accordance with embodiments of the present invention. More specifically, with reference to FIG. 1A, the semiconductor structure 100 comprises a substrate 110, interposers 120, 122, 124, 130, 132, and 134 on the substrate 110, semiconductor chips (integrated circuits) 126, 136, and 138, and a bridge 115. In one embodiment, the semiconductor chip 136 is a microprocessor, the semiconductor chip 138 is a memory interfacing chip, and the semiconductor chip 126 is a memory chip.

[0015] In one embodiment, the interposer 130 comprises multiple interconnect layers (not shown in FIG. 1A but can be seen in FIGS. 1Bi and 1Bii). FIG. 1Bi shows a cross-section view of a portion of the interposer 130, in accordance with embodiments of the present invention. The thickness of the interposer 130 can be less than the thickness of the wafer from which the interposer 130 is formed. For instance, the thickness of the interposer 130 can be in a range of 10 μ m to 100 μ m, whereas the thickness of the wafer can be 700 μ m. With reference to FIGS. 1A and 1Bi, the interposer 130 comprises interconnect layers 130a and 130b, solder balls 130' and 130'', and backside pads 131. The interconnect layer 130a comprises electrically conductive wires 130a'' and vias 130a'. Similarly, the interconnect layer 130b comprises electrically conductive wires 130b'' and vias 130b'.

[0016] In one embodiment, the electrically conductive wires 130a'' and 130b'' run in directions that are perpendicular to a reference direction 112 (the reference direction 112 is perpendicular to the top surface 110'' of the substrate 110). The vias 130a' and 130b' provide electrical paths between neighboring interconnect layers. For example, the vias 130b' provide electrical paths between the electrically conductive wires 130a'' and 130b'' of the interconnect layers 130a and 130b, respectively. The vias 130a' and 130b' can be traditional Front-End-Of-Line (FEOL) vias or Back-End-Of-Line (BEOL) vias. The electrically conductive wires 130a'' and 130b'' and the vias 130a' and 130b' comprise an electrically conductive material such as copper. The solder balls 130' and 130'' are electrically connected to the backside pads 131. The solder balls 130' and 130'' can comprise tin, lead, or a mixture of them, whereas the backside pads 131 can comprise aluminum.

[0017] In one embodiment, the solder balls 130' of the interposer 130 are physically attached to substrate pads (not shown) of the substrate 110. The substrate pads of the substrate 110 are electrically connected to substrate balls 110' of the substrate 110. The backside pads 131 of the interposer 130 are physically attached to solder balls 132' of the interposer 132 and solder balls 138' of the semiconductor chip 138.

[0018] FIG. 1Bii shows an alternative embodiment of the interposer 130 of FIG. 1Bi. More specifically, the interposer 130 of FIG. 1Bii is similar to the interposer 130 of FIG. 1Bi except that the interposer 130 of FIG. 1Bii comprises a device layer 130d. With reference to FIG. 1Bii, the device layer 130d can comprise a device 135. The device 135 can comprise transistors, capacitors, resistors, or a combination of them. For example, the device can be an integrated circuit. The device 135 can be electrically connected to the backside pads 131 through electrical paths (not shown). The device 135 can

also be electrically connected to the solder balls **130'** of the interposer **130** through the interconnect layers **130a** and **130b**. The interposer **130** of FIG. 1Bii can be referred to as a semiconductor chip **130**. The structures **130** of FIGS. 1Bi and 1Bii can be formed by conventional methods. In one embodiment, the semiconductor chip **130** of FIG. 1Bii can be one of the following: a memory interface chip, a switch chip, an optoelectronic transceiver chip, a photo detector chip, an application specific integrated circuit (ASIC) chip, or a field programmable gate array (FPGA) chip.

[0019] In one embodiment, each of the interposers **120**, **122**, **124**, **132**, and **134** and the bridge **115** is similar to either the interposer **130** of FIG. 1Bi or the semiconductor chip **130** of FIG. 1Bii. As a result, in one embodiment, some of the interposers **120**, **122**, **124**, **130**, **132**, and **134** and the bridge **115** are semiconductor chips (similar to the semiconductor chip **130** of FIG. 1Bii), and the others are interposers without any device (similar to the interposer **130** of FIG. 1Bi). In one embodiment, the interposer **132** is a voltage regulation chip **132**, and the interposer **134** is a cache memory chip **134**.

[0020] In one embodiment, the substrate **110** can be a ceramic substrate or an organic substrate. The substrate **110** can comprise multiple interconnect layers (not shown but similar to the interconnect layers **130a** and **130b** of FIG. 1Bi). The interposers **120** and **130** are electrically connected to the substrate **110** through solder balls **120'** and **130'** of the interposers **120** and **130**, respectively. The semiconductor chip **138** is electrically connected to the interposer **130** through solder balls **138'** of the semiconductor chip **138**. The semiconductor chip **126** is electrically connected to the interposer **120** through the interposers **120**, **122**, and **124**. Similarly, the semiconductor chip **136** is electrically connected to the interposers **130** through the voltage regulation chip **132** and the cache memory chip **134**.

[0021] In one embodiment, the interposer **124** is electrically connected to the interposer **122** through solder balls **124'** of the interposer **124**, and the interposer layer **122** is electrically connected to the interposer **120** through solder balls **122'** of the interposer **122**. Similarly, the processor chip **136** is attached via solder interconnections to the cache memory chip or memory interface chip **134** which is electrically connected to one or more other cache memory chips, memory interface chips and/or a voltage regulation chip such as silicon package interposer layers **132** and **130** (and additional layers as needed but not shown) using solder balls.

[0022] In one embodiment, the interposers **120** and **130** are electrically connected to each other through the bridge **115**. More specifically, the interposer **120** is electrically connected to the bridge **115** through solder balls **115'+120''**, and the interposer **130** is electrically connected to the bridge **115** through solder balls **115'+130''**. The solder balls **115'+120''** result from solder balls **115'** of the bridge **115** and the solder balls **120''** of the interposer **120** being bonded together. Similarly, the solder balls **115'+130''** result from the solder balls **115'** of the bridge **115** and the solder balls **130''** of the interposer **130** being bonded together. Alternatives for bonding include use of solder from one component to a pad on an adjacent layer of strata, solder to solder interconnection or use of alternate electrical and thermal interconnection material.

[0023] In one embodiment, the fabrication process of the structure **100** is as follows. The substrate **110** is formed having the substrate balls **110'** as shown. The substrate **110** with its substrate balls **110'** can be formed by a conventional method. Similarly, the semiconductor chips **136**, **138**, and

126 are separately formed having their respective solder balls **136'**, **138'**, and **126'** thereon as shown. The interposers **130**, **120**, **122**, and **124** can be separately formed having their respective solder balls **130'**, **130''**, **120'**, **120''**, **122'**, and **124'** thereon as shown. The voltage regulation chip **132** and the cache memory chip **134** can be separately formed having their respective solder balls **132'** and **134'** thereon as shown. The bridge **115** with its solder balls **115'** can also be separately formed.

[0024] Next, in one embodiment, the semiconductor chip **136** is physically attached to the cache memory chip **134** by physically attaching the solder balls **136'** of the semiconductor chip **136** to backside pads (not shown) of the cache memory chip **134** resulting in a chip stack **136+134**. The semiconductor chip **136** can be attached to the cache memory chip **134** by a conventional flip-chip technology. More specifically, the semiconductor chip **136** can be attached to the cache memory chip **134** at a pressure of from 0 to 200 PSI with temperature of about 300 to 450 C and with a controlled ambient such as N₂, Forming Gas mix of Nitrogen and Hydrogen or alternate ambient, such that the solder balls **136'** melt and bond to the backside pads of the cache memory chip **134** resulting in the chip stack **136+134**. Then, the chip stack **136+134** is cooled down. Then, the chip stack **136+134** can be tested by a first test process. Assume that the chip stack **136+134** passes the first test process.

[0025] Next, in one embodiment, the chip stack **136+134** is physically attached to the voltage regulation chip **132** by attaching the solder balls **134'** of the cache memory chip **134** to the backside pads (not shown) of the voltage regulation chip **132** resulting in a chip stack **136+134+132**. More specifically, the chip stack **136+134** can be attached to the voltage regulation chip **132** by a conventional flip-chip technology. Then, the chip stack **136+134+132** can be tested by a second test process. Assume that the chip stack **136+134+132** passes the second test process.

[0026] Next, in one embodiment, the chip stack **136+134+132** is physically attached to the interposer layer **130** by physically attaching the solder balls **132'** of the voltage regulation chip **132** to the backside pads (not shown) of the interposer **130** resulting in a chip stack **136+134+132+130**. More specifically, the chip stack **136+134+132** can be attached to the interposer **130** by a conventional flip-chip technology. Then, the chip stack **136+136+132+130** can be tested by a third test process. Assume that the chip stack **136+134+132+130** passes the third test process. In one embodiment, the chip stack assembly or chip stack and interposer assembly (such as **136**, **134**, **132** and **130** in one example) may be either fully assembled and tested for a known good die stack or partially assembled and tested, further assembled with other die or die stack subcomponents and then tested depending upon the complexity of the die, their yield, any redundancy built into the vertical interconnection layers and circuits, the assembly approach which may consist of die to die, die to package, die to wafer or wafer to wafer assembly processes chosen for specific applications.

[0027] Next, in one embodiment, the semiconductor chip **138** is physically attached to the interposer **130** by physically attaching the solder balls **138'** of the semiconductor chip **138** to the backside pads (not shown) of the interposer **130** resulting in a first chip block **136+134+132+130+138**. More specifically, the semiconductor chip **138** can be attached to the interposer **130** by a conventional flip-chip technology. Then, the first chip block **136+134+132+130+138** can be tested by

a fourth test process. Assume that the first chip block **136+134+132+130+138** passes the fourth test process.

[0028] In one embodiment, separately from the formation of the first chip block **136+134+132+130+138**, the semiconductor chip **126** and the interposers **124**, **122**, and **120** are in turn attached together, as shown in FIG. 1A, resulting in a second chip block **126+124+122+120**. More specifically, the semiconductor chip **126** and the interposers **124**, **122**, and **120** are attached together in a manner similar to the manner in which the semiconductor chip **136**, the cache memory chip **134**, the voltage regulation chip **132**, and the interposer **130** are attached together. Then, the second chip block **126+124+122+120** can be tested by a fifth test process. Assume that the second chip block **126+124+122+120** passes the fifth test process.

[0029] In one embodiment, the bridge **115** is attached to the substrate **110** such that the top surface **115'** of the bridge **115** and the top surface **110''** of the substrate are coplanar. If the substrate **110** is a ceramic substrate, then the ceramic substrate **110** can be ground so as to create a space to accommodate the bridge **115**. Then, the bridge **115** can be attached to the ceramic substrate **110** by an adhesive material. If the substrate **110** is an organic substrate, then the bridge **115** is attached to the organic substrate **110** by pressing the bridge **115** into the organic substrate **110** (with an adhesive material between them).

[0030] Next, in one embodiment, the first chip block **136+134+132+130+138** is attached to the substrate **110** and the bridge **115** by simultaneously attaching the solder balls **130'** and **130''** of the interposer **130** to substrate pads (not shown) of the substrate **110** and the solder balls **115'** of the bridge **115**. It should be noted that, during this attachment process, two solder balls **130''** bond to two solder balls **115'** resulting in the two bonded solder balls **115'+130''** as shown.

[0031] Similarly, the second chip block **126+124+122+120** is attached to the substrate **110** and the bridge **115** by simultaneously attaching the solder balls **120'** and **120''** of the interposer **120** to substrate pads (not shown) of the substrate **110** and the solder balls **115'** of the bridge **115**. It should be noted that, during this attachment process, two solder balls **120''** merge two solder balls **115'** resulting in the two bonded solder balls **115'+120''** as shown. In one embodiment, the attachment of the first chip block **136+134+132+130+138** to the substrate **110** and the bridge **115** and the attachment of the second chip block **126+124+122+120** to the substrate **110** and the bridge **115** can be performed simultaneously. Then, the structure **100** can be tested by a sixth test process.

[0032] In summary, the structure **100** is formed by attaching different components (the semiconductor chips **136**, **138**, and **126**, the cache memory chip **134**, the voltage regulation chip **132**, the interposers **130**, **124**, **122**, and **120**, the bridge **115** and the substrate **110**) together. Each component can be independently tested after its formation. After a component or a block of components is attached to another component or another block of components, testing can be done for the resulting block of components.

[0033] FIG. 1C shows a top-down view of the structure **100** of FIG. 1A. With reference to FIGS. 1A and 1C, for simplicity, only the substrate **110**, the interposers **120** and **130**, and the bridge **115** of FIG. 1A are shown in FIG. 1C, whereas the chips **136**, **138**, and **126** and the cache memory chip **134**, the voltage regulation chip **132**, and interposers **124** and **122** of FIG. 1A are not shown in FIG. 1C.

[0034] In the embodiments described above, it is assumed that the first chip block **136+134+132+130+138** passes the fourth test process after its formation. Alternatively, if the first chip block **136+134+132+130+138** fails the fourth test process, then it is replaced by another first chip block **136+134+132+130+138** and then the fourth test process is performed again.

[0035] In the embodiments described above, the semiconductor chip **136**, the cache memory chip **134**, the voltage regulation chip **132**, and the interposer **130** are attached together in the order described above. Alternatively, the semiconductor chip **136**, the cache memory chip **134**, the voltage regulation chip **132**, and the interposer **130** are attached together in a different order. More specifically, the voltage regulation chip **132** is attached to the interposer **130** resulting in a chip stack **130+132**. Next, the cache memory chip **134** is attached to the chip stack **130+132** resulting in a chip stack **130+132+134**. Then, the semiconductor chip **136** is attached to the chip stack **130+132+134** resulting in the chip stack **130+132+134+136**. Similarly, the semiconductor chip **126**, the interposers **124**, **122**, and **120** can be attached together in an order different than that described above.

[0036] FIG. 2 shows a cross-section view of a semiconductor structure **200**, in accordance with embodiments of the present invention. More specifically, with reference to FIG. 2, the structure **200** is similar to the structure **100** of FIG. 1A except that the bridge **215** is placed on the top surface **110''** of the substrate **110**. More specifically, the bridge **215** can be physically attached to the top surface **110''** of the substrate **110** by an adhesive material.

[0037] In one embodiment, the fabrication process of the structure **200** is similar to the fabrication process of the structure **100** of FIG. 1A except that the bridge **215** is physically attached to the substrate **110** only by an adhesive material whether the substrate **110** is a ceramic substrate or an organic substrate. It should be noted that merged solder balls **215'+130''** and **215'+120''** of FIG. 2 are smaller than the bonded solder balls **115'+130''** and **115'+120''** of FIG. 1A. In one embodiment, the bridge **215** of FIG. 2 is similar to the bridge **115** of FIG. 1A except that the bridge **215** is thinner than the bridge **115** in the reference direction **112** so as to create more space for the merged solder balls **215'+130''** and **215'+120''**.

[0038] FIG. 3 shows a cross-section view of a semiconductor structure **300**, in accordance with embodiments of the present invention. More specifically, with reference to FIG. 3, the structure **300** is similar to the structure **100** of FIG. 1A except that the top surface **315''** of the bridge **315** and the top surface **110''** of the substrate **110** are not coplanar. The bridge **315** can be similar to the bridge **115** but thicker than the bridge **115** in the reference direction **112**. In one embodiment, the fabrication process of the structure **300** is similar to the fabrication process of the structure **100** of FIG. 1A.

[0039] FIG. 4 shows a cross-section view of a semiconductor structure **400**, in accordance with embodiments of the present invention. More specifically, with reference to FIG. 4, the structure **400** is similar to the structure **100** of FIG. 1A except that the bridge **415** is physically attached to the interposers **120** and **130** by physically attaching the solder balls **415'** of the bridge **415** to the backside pads (not shown) of the interposer **120** and **130**. In one embodiment, the bridge **415** may be the full thickness from the wafer it was fabricated from (not shown) or the same thickness as other die or die stacks on top of the interposer(s).

[0040] In one embodiment, the fabrication process of the structure **400** is similar to the fabrication process of the FIG. **1A** except that the bridge **415** is attached to the interposers **120** and **130** after the interposers **120** and **130** are attached to the substrate **110**.

[0041] FIG. **5** shows a cross-section view of a semiconductor structure **500**, in accordance with embodiments of the present invention. More specifically, with reference to FIG. **5**, the structure **500** is similar to the structure **100** of FIG. **1A** except that (i) the bridge **115** is omitted and (ii) the semiconductor chip **138** plays the role of a bridge electrically connecting the interposers **120** and **130** together. More specifically, the solder balls **138'** of the semiconductor chip **138** are physically attached to backside pads (not shown) of the interposers **120** and **130**.

[0042] In one embodiment, the fabrication process of the structure **500** is similar to the structure **100** of FIG. **1A** except that the semiconductor chip **138** is attached to both the interposers **120** and **130** after the chip block **136+134+132+130** and the chip block **126+124+122+120** are attached to the substrate **110**. After the chip block **136+134+132+130** and the chip block **126+124+122+120** are attached to the substrate **110**, the semiconductor chip **138** is physically attached to the interposers **120** and **130** simultaneously by a conventional flip-chip technology,

[0043] In the embodiments described above, with reference to FIG. **1A**, the solder balls **120''** and **130''** of the interposers **120** and **130**, respectively, are bonded one-to-one to the solder balls **115'** of the bridge **115**. Alternatively, the solder balls **115'** of the bridge **115** are replaced by bridge pads therein and the solder balls **120''** and **130''** of the interposers **120** and **130**, respectively, are bonded one-to-one to the bridge pads of the bridge **115**. The bridge pads can comprise an electrically conductive material such as aluminum.

[0044] In the embodiments described above, there are two interposers **120** and **130** attached to the substrate **110**. In general, *N* interposers can be attached to the substrate **110**, wherein *N* is a positive integer. The *N* interposers can be electrically connected together through bridges and solder balls (similar to the bridge **115** and the solder balls **115'+120''** and **115'+130''** of FIG. **1A**). For example, FIG. **6** shows a top-down view of a semiconductor structure **600**, in accordance with embodiments of the present invention. More specifically, with reference to FIG. **6**, the structure **600** comprises four interposers **620**, **630**, **640**, and **650** and four bridges **615a**, **615b**, **615c**, and **615d**. The interposer **620** and **630** are electrically connected to each other through the bridge **615a**. The interposer **620** and **650** are electrically connected to each other through the bridge **615d**. The interposer **630** and **640** are electrically connected to each other through the bridge **615b**. The interposer **640** and **650** are electrically connected to each other through the bridge **615c**.

[0045] In the embodiments described above, with reference to FIG. **1A**, the semiconductor chip **136** is a microprocessor, the semiconductor chip **138** is a memory interfacing chip, and the semiconductor chip **126** is a memory chip. Alternatively, the dies/chips or die stacks in FIG. **1A** may serve other functions than microprocessor and memory or cache such as memory interface die, application specific integrated circuit die, opto-electronic die, photo detectors, communications switch chips, and/or other functional die or integrated heterogeneous die.

[0046] In the embodiments described above, with reference to FIG. **1A**, the interposer **130** is connected to the substrate

110 by the connection of the solder balls **130'** of the interposer **130** and the substrate pads of the substrate **110** (i.e., solder ball-to-pad interconnections), whereas the interposer **130** is connected to the bridge **115** by the connection of the solder balls **130''** of the interposer **130** and the solder balls **115'** of the bridge **115** (solder ball-to-solder ball interconnections). Similarly, the electrical connections between two interposers (e.g., the interposers **132** and **130**) or between a chip and an interposer (e.g., the chip **136** and the interposer **134**) are solder ball-to-pad interconnections. In general, the connections between the interposer **130** and the substrate **110**, between the interposer **130** and the bridge **115**, between two interposers, and between a chip and an interposer are one of the following: solder ball-to-solder ball interconnections, solder ball-to-pad interconnections, stud-to-pad interconnections. Each of the solder ball, the pad, and the stud can be referred to as a connector.

[0047] In the embodiments described above, with reference to FIGS. **1Bi** and **1Bii**, the solder balls **130'** of the interposer **130** are electrically connected to the backside pads **131** of the interposer **130** through interconnect layers **130b** and **130c** and the device layer **130d**. Alternatively, the solder balls **130'** are electrically connected to the backside pads **131** through a vertical through-silicon-via (TSV).

[0048] In the embodiments described above, the solder balls **130'** and **130''** can comprise tin, lead, or a mixture of them, whereas the backside pads **131** can comprise aluminum. In general, the solder balls can comprise tin, silver, gold, or a mixture of them, the pads can comprise copper, gold, nickel, or a mixture of them, whereas the stud can comprise copper.

[0049] While particular embodiments of the present invention have been described herein for purposes of illustration, many modifications and changes will become apparent to those skilled in the art. Accordingly, the appended claims are intended to encompass all such modifications and changes as fall within the true spirit and scope of this invention.

What is claimed is:

1. A structure, comprising:

a substrate;
a first interposer on the substrate, wherein the first interposer is electrically connected to the substrate;
a second interposer on the substrate, wherein the second interposer is electrically connected to the substrate; and
a first bridge electrically connected to the first and second interposers.

2. The structure of claim **1**,

wherein the substrate comprises substrate connectors, wherein the first interposer comprises first interposer connectors, wherein the second interposer comprises second interposer connectors, wherein the first and second interposer connectors are electrically connected to the substrate connectors, and wherein each connector of the substrate connectors, the first interposer connectors, and the second interposer connectors comprises one selected from the group consisting of a solder ball, a pad, and a stud.

3. The structure of claim **2**,

wherein the first interposer further comprises first bonding connectors, wherein the second interposer further comprises second bonding connectors, wherein the first bridge comprises bridge connectors,

wherein the first and second bonding connectors are in direct physical contact one-to-one with the bridge connectors, and

wherein each connector of the first bonding connectors, the second bonding connectors, and the bridge connectors comprises one selected from the group consisting of a solder ball, a pad, and a stud.

4. The structure of claim **3**, further comprising a third interposer on the first interposer, wherein the third interposer is electrically connected to the first interposer.

5. The structure of claim **4**, further comprising a fourth interposer on the first interposer, wherein the fourth interposer is electrically connected to the first interposer, and

wherein each interposer of the first, second, third, and fourth interposers comprises at least a transistor.

6. The structure of claim **2**, wherein the first interposer further comprises first bonding connectors, wherein the second interposer further comprises second bonding connectors, wherein the first bridge comprises bridge connectors, wherein the first and second bonding connectors are in direct physical contact one-to-one with the bridge connectors, and

wherein each connector of the first bonding connectors, the second bonding connectors, and the bridge connectors comprises one selected from the group consisting of a solder ball, a pad, and a stud.

7. The structure of claim **1**, wherein the first bridge is in direct physical contact with the substrate.

8. The structure of claim **7**, wherein a first top surface of the substrate and a second top surface of the first bridge are coplanar.

9. The structure of claim **1**, wherein the first bridge comprises bridge connectors, wherein the first interposer comprises first interposer connectors, wherein the second interposer comprises second interposer connectors, wherein the bridge connectors are in direct physical contact one-to-one with the first and second interposer connectors, and

wherein each connector of the first interposer connectors, the second interposer connectors, and the bridge connectors comprises one selected from the group consisting of a solder ball, a pad, and a stud.

10. The structure of claim **9**, wherein the first bridge comprises an integrated circuit.

11. The structure of claim **1**, further comprising: a fifth interposer on the substrate, wherein the fifth interposer is electrically connected to the substrate; and a second bridge electrically connected to the first and fifth interposers.

12. A structure, comprising:
a substrate;
a first interposer on the substrate, wherein the first interposer is electrically connected to the substrate;
a second interposer on the substrate, wherein the second interposer is electrically connected to the substrate; and a first bridge electrically connected to the first and second interposers,
wherein the substrate comprises substrate connectors, wherein the first interposer comprises first interposer connectors,

wherein the second interposer comprises second interposer connectors,
wherein the first and second interposer connectors are electrically connected to the substrate connectors,
wherein the first bridge is in direct physical contact with the substrate, and

wherein each connector of the first interposer connectors, the second interposer connectors, and the bridge connectors comprises one selected from the group consisting of a solder ball, a pad, and a stud.

13. The structure of claim **12**, further comprising a third interposer on the first interposer, wherein the third interposer is electrically connected to the first interposer.

14. The structure of claim **13**, further comprising a fourth interposer on the first interposer, wherein the fourth interposer is electrically connected to the first interposer.

15. The structure of claim **12**, further comprising:
a fifth interposer on the substrate, wherein the fifth interposer is electrically connected to the substrate; and
a second bridge electrically connected to the first and fifth interposers.

16. A structure formation method, comprising:
providing (i) a substrate, (ii) a first interposer, (iii) a second interposer, and (iv) a bridge; and
attaching the substrate, the first interposer, the second interposer, and the bridge together, wherein the first interposer is electrically connected to the substrate,
wherein the second interposer is electrically connected to the substrate, and
wherein the bridge is electrically connected to the first and second interposers.

17. The method of claim **16**, further comprising:
providing a third interposer; and
attaching the third interposer to the first interposer, wherein the third interposer is electrically connected to the first interposer.

18. The method of claim **16**, wherein said attaching the substrate, the first interposer, the second interposer, and the bridge together comprises:
attaching the bridge to the substrate;
after said attaching the bridge to the substrate is performed, attaching the first interposer to both the substrate and the bridge; and
after said attaching the bridge to the substrate is performed, attaching the second interposer to both the substrate and the bridge.

19. The method of claim **16**, wherein said attaching the substrate, the first interposer, the second interposer, and the bridge together comprises:
attaching the first and second interposers to the substrate; and
after said attaching the first and second interposers to the substrate is performed, attaching the bridge to the first and second interposers.

20. The method of claim **16**, wherein the bridge comprises an integrated circuit.